### January • February
3D - Wafer-Level Packaging - MEMS

<table>
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<th>Columns</th>
<th>Technical Features</th>
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<tr>
<td>Semiconductor Industry Forecast</td>
<td>Probe Technology Advances</td>
<td>• BITS Workshop</td>
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<td></td>
<td></td>
<td>Mesa, AZ (March 9-12)</td>
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<tr>
<td>Competitive Strategies and Tactics for the</td>
<td>Probing µ-bumps for wide I/O 3D SICs</td>
<td>• IMAPS Device Packaging (DPC)</td>
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<tr>
<td>Packaging Industry</td>
<td></td>
<td>Fountain Hills, AZ (March 10-13)</td>
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<tr>
<td>Putting 2.5D in Perspective</td>
<td>MEMS Mobile Devices</td>
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<td>Bringing New Electronic Materials to Market</td>
<td>3D IC Stacking</td>
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<td>BGA Socket Systems for Test and Verification</td>
<td>Next-generation TSV Filling by Electroplating</td>
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**R&D Institute Profile**

**Ad Space Close Jan 21 - Ad Materials Deadline Jan 24**

### March • April
OSATS – Packaging & Assembly – 3D TSVs

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<th>OSATS Market Update</th>
<th>European Assembly and Test</th>
<th>• SEMICON China</th>
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<tr>
<td>IC Packaging Technologies &amp; Trends</td>
<td>3D TSV &amp; Heterogeneous Integration</td>
<td>Shanghai China (March 18-20)</td>
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<td>How the OSATs Stack Up</td>
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<td>• APEX Expo</td>
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<td>High-density 2.5D Interposer Market Update</td>
<td>Dispensing Trends</td>
<td>Las Vegas, NV (March 25-27)</td>
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<tr>
<td>TSV Reliability Challenges</td>
<td>Glass as a Future Packaging Platform</td>
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<td></td>
<td>Die &amp; Flip-chip Bonding</td>
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<tr>
<td></td>
<td>Semiconductor Packaging Materials</td>
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<td>Advancements in PoP Technology</td>
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**R&D Institute Profile**

International Directory of IC Packaging Foundries

**Ad Space Close Feb 11 - Materials Close Feb 14**

### May • June
Materials - Test & Burn-in Sockets - 3D IC Integration

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<th>3DIC &amp; TSV Interconnects</th>
<th>• MEPTEC</th>
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<td>Standards Update</td>
<td>Enabling Technologies for 2.5D IC/ Si Integration</td>
<td>Symposium on Polymers</td>
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<td>Wilmington, DE (May 6-8)</td>
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<tr>
<td>Patents Update</td>
<td>3D Integration of SiP</td>
<td>• MEMS Tech Symposium</td>
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<td>San Jose, CA (May 22)</td>
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<td>High Performance Test Sockets</td>
<td>• ECTC</td>
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<td></td>
<td>Bond Testing</td>
<td>Lake Buena Vista, FL (May 27-30)</td>
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<tr>
<td></td>
<td>Metrology Trends</td>
<td>• IEEE/SW Test Workshop (SWTW)</td>
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<td>TSV Interposers</td>
<td>San Diego, CA (June 6-11)</td>
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<td></td>
<td>Laser Ablation Technology</td>
<td>• SEMICON West</td>
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<td>San Francisco, CA (July 8-10)</td>
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**Special Feature: R&D Institute Profile**

**Ad Space Close March 28 - Ad Materials Close April 2**

**Special Feature: Executive Profile & Perspective**

For ad inquiries: ads@chipscalereview.com - For editorial inquiries editor@chipscalereview.com

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### July ● August

**Copper Pillar Bumping - Dicing & Singulation - Assembly & Test**

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<th>Trade Show /Conferences</th>
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<tr>
<td>Assembly &amp; Test Market Update</td>
<td>Copper Pillar Bumping</td>
<td>• SEMICON Taiwan Tampa, Taiwan (Sept 3-5)</td>
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<td>• MEPTEC Medical Microelectronics Conference Portland, OR (Sept 18-19)</td>
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<tr>
<td>Burn in and Test Market Update</td>
<td>Scalable Approaches for 2.5D IC Assembly</td>
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<td>Cost Reduction of MEMS</td>
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<td>Bonding/De-Bonding/Wafer-thinning Handling</td>
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<td>Dicing &amp; Singulation</td>
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<td>Spring Contact Probes in Wafer Test Applications</td>
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<td>Solder Trends</td>
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#### International Directory of Test and Burn-in Sockets

*Ad Space Close May 30 - Ad Materials Close Jun 4*

### September ● October

**Thermocompression Bonding – Wafer Probing – Wire Bonding**

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<tr>
<th>Test Trends</th>
<th>TCB for 2.5D/3D Assembly</th>
<th>• SMTA International Rosemont, IL (Sept 28-Oct 2)</th>
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<tr>
<td>Patents</td>
<td>3D Packaging Through-glass Vias (TGV)</td>
<td>• SEMICON Europa Grenoble, France (Oct 7-9)</td>
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<td></td>
<td>Wafer Probers &amp; Probe Cards</td>
<td>• IMAPS Microelectronics Symposium San Diego, CA (Oct 13-16)</td>
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<td></td>
<td>High-reliability Wire Bonding</td>
<td>• T-Sensors Summit San Diego, CA (Oct 15-16)</td>
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<td>• International Test Conference (ITC) Seattle WA (Oct 21-24)</td>
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<td>• MEMS Executive Congress Scottsdale, AZ (Nov 5-7)</td>
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<td></td>
<td>• IWLPC-International Wafer-Level Packaging Conference &amp; Exhibition San Jose, CA (Nov 11-13)</td>
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#### International Directory of Bonding Equipment for 2.5D and 3D Assembly

*Ad Space Close Aug 8 - Ad Materials Close Aug 13*

**Special Feature: Executive Profile & Perspective**

### November ● December

**3D TSVs – Package Test – Inspection**

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<th>Advances in Burn-in &amp; Test Sockets</th>
<th>Heterogeneous Integration Through-die Stacking</th>
<th>• MEPTEC Packaging, Assembly &amp; Test Conf. Santa Clara, CA (Nov TBD)</th>
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<tbody>
<tr>
<td>Green Electronics</td>
<td>3D TSVs</td>
<td>• SEMICON Japan Tokyo, Japan (Dec 3-5)</td>
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<tr>
<td>MEMS Industry Report</td>
<td>HVM of 3D ICs</td>
<td>• RTI 3D ASIP Conference Burlingame, CA (Dec 10-12)</td>
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<td>Solder Ball Placement</td>
<td>• SEMI European 3D TSV Summit Grenoble France (Jan 2015)</td>
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<td>Reliable Flip-chip Interconnection</td>
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<td></td>
<td>Package Inspection</td>
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<td>Failure Analysis</td>
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*Ad Space Close Oct 10 - Materials Close Oct 15*